Preface

About This Report

Winbond Electronics Corporation (referred to as "Winbond") publishes the 2025 Sustainability Report (hereinafter referred to as "this Report") to transparently and comprehensively disclose the impacts of its operations across the three ESG dimensions—Environmental, Social, and Governance—as well as its sustainability-related strategies and actions.
Through its business activities, communications, and stakeholder engagement, Winbond translates sustainability commitments into operational practices and responds to stakeholder expectations regarding sustainable development and long-term corporate value creation.

Reporting Framework

This Report has been prepared with reference to the following international and domestic sustainability reporting standards and guidelines:

- Global Reporting Initiative (GRI Standards)
- Sustainability Accounting Standards Board (SASB) – Semiconductors Sustainability Accounting Standard (2018)
- Task Force on Climate-related Financial Disclosures (TCFD)
- Taiwan Stock Exchange Regulations Governing the Preparation and Filing of Sustainability Reports by Listed Companies
- AA1000 Accountability Principles
- United Nations Global Compact

Management Procedures

Winbond has incorporated sustainability information compilation into its internal control and governance framework. Sustainability-related data is collected, reviewed, and approved in accordance with established procedures to ensure consistency, accuracy, and reliability.

1. Annual performance review.
2. Confirmation of disclosure priorities through cross-functional engagement, with material issues serving as the focus of data collection.
3. Report compilation led by the ESG Office, with sustainability practice content drafted by functional teams and reviewed by team leaders.
4. Third-party assurance: In April 2026, the Report was independently assured by BSI Taiwan in accordance with AA1000AS v3 Type II (High Assurance). For details, please refer to Appendix 9: Independent Assurance Statement.
5. Review and approval by the President, Chairman, and Sustainable Development Committee.
6. Board-level reporting: The Sustainable Development Committee, chaired by the Chairman, oversees five functional teams and reports sustainability progress to the Board on a quarterly basis.
7. Public disclosure through the Company' s ESG website.

Reporting Period, Boundary, and Scope

The reporting period covers January 1 to December 31, 2025.

The reporting boundary is consistent with the consolidated financial statements and includes Winbond (Taiwan) fabs and offices (Central Taiwan Science Park Fab, Kaohsiung Fab, Zhubei Building, Taipei Office, and Tainan Office), Winbond subsidiaries, Nuvoton Technology (Taiwan), Nuvoton Technology (Japan), and Nuvoton subsidiaries (collectively, the "Winbond Group"). Any deviation from this scope is disclosed in the relevant sections.

- Nuvoton publishes its own independent sustainability report. Please refer to the Nuvoton 2025 ESG Report

Information restatement

Because the reporting boundary has been expanded to cover the entire Group, the data differ slightly from previous periods. To enhance comparability, historical data has been updated accordingly.

Publication schedule

Winbond publishes its sustainability report annually. The 2025 report represents the 12th edition. To support energy conservation and carbon reduction, Winbond adopts a paperless approach and publishes this Report electronically.

- Current edition: August 2026
- Previous edition: August 2025
- Next scheduled edition: August 2027

Contact information

If you have any questions or suggestions regarding this Report, please feel free to contact us. Our contact details are as follows:

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- Website: www.winbond.com
- ESG website: esg.winbond.com

Website

Message from our Chairman

"Sustainability," for Winbond, is a multifaceted concept. It is an enduring corporate spirit to be passed down for a hundred years and beyond. It safeguards our ability to continuously create value in an ever-changing world, inspiring us to become a pillar of sustainable development for human society. It reminds us to use resources wisely and to cherish the only planet we have.

A Shifting Global Landscape: Prosperity and Trials in the Semiconductor Arena

In 2025, the global semiconductor market entered a new era driven by AI technology. From cloud servers to edge computing, the surging demand for high-speed data processing brought unprecedented challenges and opportunities to the memory market. Meanwhile, geopolitical risks and supply chain uncertainties persisted, and the imbalance between market supply and demand tested the resilience and strategic acumen of every enterprise. Facing a rapidly shifting market, Winbond takes a long-term perspective on industry cycles and technological revolutions. Guided by our dual axes of "Sustainability" and "Digital," we navigate change with steadiness and meet challenges head-on with innovation.

In 2025, Winbond continued to demonstrate resilience and innovation. On the technology front, our CMS 16 nm DRAM process and Flash 24 nm NAND products successfully completed CPR, while our 45 nm NOR and Secure Flash products expanded into new markets. Winbond continued to deepen its presence in the secure memory domain, with Secure Flash integrating Post-Quantum Cryptography (PQC) technology to enhance product security. Our process optimization efforts were recognized with the TCIA Gold Tower Five-Star Award, demonstrating steady improvement in manufacturing capabilities. We also launched 8Gb DDR4 DRAM on the 16 nm process node, delivering higher speed and improved power efficiency, further expanding our footprint in the industrial control and embedded markets.

Amid Transformation and Challenges, Winbond Strengthens Its ESG Foundations Across 3 Dimensions

Our vision has always been clear: "Be a hidden champion in providing sustainable semiconductors to enrich human life." From our SBTi net zero commitment and renewable energy deployment to green product innovation, Winbond is dedicated to creating a lower-carbon future. Through the collective efforts of all employees, we not only passed the SBTi greenhouse gas reduction target validation, but also achieved double "A" ratings in both "Climate Change" and "Water Security" from CDP for the first time, along with an "A" Leadership rating in the "Supplier Engagement Assessment"—elevating Winbond to the ranks of the world's top sustainability leaders.

Furthermore, we place great emphasis on the shared growth of employees and the company. All Winbond employees are the driving force behind our corporate sustainability practices. In 2025, we completed global human rights training and adopted a multi-pronged approach encompassing training and employee benefits to enhance employee satisfaction and engagement, building a solid talent foundation for our sustainability initiatives. On the governance front, Winbond was selected as one of the Top 100 Global Innovators for the third consecutive year, was included in the S&P Dow Jones Best-in-Class World Index for the first time, and secured a NT$25 billion sustainability-linked syndicated loan with the endorsement of 17 banks—closely aligning our financial strategy with ESG metrics, demonstrating robust governance and laying a strong foundation for future competitiveness.

Riding the Momentum: Envisioning a Future Where Sustainability and Digital Transformation Advance Together

Over the next 50 years, AI and industry transformation will bring tremendous innovation and change. Winbond will pursue a dual-axis transformation—empowering sustainability through technology and driving process advancement through sustainability goals. We will continue to align with international standards to enhance competitiveness, fully commit to SBTi's pathway toward net zero by 2050, and build an attractive workplace on the global stage. Winbond will advance alongside technology and sustainability, walking hand in hand with customers, suppliers, and all stakeholders, moving steadily forward through times of change, and building a cleaner, smarter future together with the world.

Chairman & CEO, Winbond Electronics

Message from our President

The global environment and industry landscape are undergoing rapid and dramatic change. Artificial intelligence technologies, geopolitical risks, and climate change continue to present significant challenges to corporate operations and governance. Guided by the vision of “Enriching human life through green semiconductor technologies,” Winbond is actively advancing its dual-axis transformation of “Sustainability” and “Digital.” Winbond demonstrates its sustainability commitments and achievements through five core pillars: from “Corporate Governance,” which strengthens integrity and risk management, to a “Sustainable Supply Chain” that partners with stakeholders to build a low-carbon ecosystem; from customer-centric “Green Product” innovation and “Environmental Sustainability” that delivers on net zero commitments, to “Human Rights and Social Inclusion” that safeguards employee well-being and promotes social welfare and nature conservation. Each pillar embodies Winbond’ s culture and vision, and is the crystallization of the joint efforts of all employees and partners.

In 2025, Winbond earned significant recognition across multiple dimensions of sustainable development: in the CDP global environmental disclosure platform, Winbond achieved the highest “A List” ratings for both “Climate Change” and “Water Security,” and was awarded the “Supplier Engagement Assessment” A Leadership level. Winbond was also included for the first time in the Dow Jones Best-in-Class Index (DJBIC), demonstrating significant progress in governance transparency and sustainability management. The Kaohsiung Fab won the Silver Award at the 7th National Enterprise Environmental Protection Award by the Ministry of Environment in its first participation, and also received the Energy Conservation Benchmark Award – Gold Award from the Ministry of Economic Affairs.

Looking ahead, we will continue to deepen our dual-axis transformation of “Sustainability” and “Digital,” working hand in hand with global supply chain partners to build a low-carbon ecosystem, deliver on ESG goals, and steadily advance our commitment to net zero emissions by 2050. We sincerely thank every employee, partner, and stakeholder who has placed their trust in Winbond, enabling us to break through challenges and move toward a more resilient and sustainable future.

President 陳沛銘

E Green Manufacturing Pioneer: Leading the Low-Carbon Future with Innovation

Extreme weather events have repeatedly impacted lives around the globe, placing greater demands on corporate social responsibility. In 2025, Winbond demonstrated its firm sustainability commitment through comprehensive decarbonization strategies and process optimization initiatives. We continued to advance intelligent energy-saving and efficiency improvement systems at our Central Taiwan and Kaohsiung Fabs, and successfully passed the Ministry of Environment’ s “Voluntary Emission Reduction Plan Review,” demonstrating outstanding achievements in energy management and low-carbon transformation.

Winbond also actively promoted green product innovation, launching PFAS-free products and creating a low-carbon supply chain through renewable-energy manufacturing. As of the end of 2025, shipments of products manufactured with renewable energy reached 451 million units, delivering total carbon reduction benefits of approximately 35,044 tCO_2e, contributing tangible momentum to global sustainable development. To enhance the accuracy of environmental management, Winbond adopted the UL 2799 standard (Zero Waste to Landfill Environmental Claim Validation) in 2025, establishing science-based, quantifiable strategies for improving resource utilization. Both the Central Taiwan and Kaohsiung Fabs achieved the highest Platinum-level certification, reflecting Winbond’ s strong commitment to waste resource recovery.

In response to the Ministry of Environment’ s “Green Cafeteria” initiative, Winbond integrated sustainability, health, and environmental principles into everyday meals. Both the Central Taiwan and Kaohsiung sites obtained certification, with the Kaohsiung site becoming the first employee cafeteria in Kaohsiung City to receive the certification.

Through these efforts, Winbond was awarded the “Net zero Industry Competitiveness Award” — Taiwan’ s first award centered on carbon neutrality and sustainability action — and ranked No. 1 in Taiwan’ s semiconductor industry on CommonWealth Magazine’ s “Corporate Carbon Reduction Thermometer” platform with an outstanding score of 1.421° C.

S People-Centric: Building a Resilient Workplace and Culture

In the semiconductor industry, talent is among the most critical competitive advantages and a key factor of corporate success. Winbond places strong emphasis on employee well-being and promotes a workplace that embraces Diversity, Equity, and Inclusion (DEI) in order to attract and retain top global talent.

In 2025, Winbond (Taiwan) and Nuvoton (Taiwan) jointly announced their participation in the “Taiwan Talent Sustainability Action Alliance,” taking concrete steps to advance human rights protection, diversity and inclusion, employee health, and career development. Internationally recognized human rights standards are embedded into daily management practices to ensure that every employee can work in a fair and respectful environment.

In terms of compensation, the average salary of Winbond’ s non-managerial employees ranks in the top 20% among listed semiconductor companies, leading the industry. Winbond also launched the “Sustainability Performance Platform,” integrating sustainability concepts into corporate culture and performance systems. In 2025, Winbond organized 55 sustainability-related courses and activities, attracting over 3,500 participations, enabling employees to practice sustainability at work and extending that influence into daily life.

Upholding the commitments of its Human Rights Policy, Winbond advanced its global human rights due diligence, with 100% completion of related education and training, institutionally safeguarding employee rights. In 2025, the“Core Values and Employee Engagement Survey” was extended to Winbond subsidiaries worldwide for the first time.

G Integrity-Driven Operations: Building the Foundation for Sustainable Value

Against the backdrop of supply chain risks and geopolitical fragmentation, corporate governance has moved beyond regulatory compliance to become the cornerstone of long-term value creation. Through innovation, transparency, and collaboration, Winbond has built a distinguished and resilient governance model.

In innovation and international recognition, Winbond has been recognized as one of the Clarivate Top 100 Global Innovators for three consecutive years, reflecting the long-term outcomes of its dedicated efforts in technology R&D and intellectual property management.

In energy strategy, Winbond is actively procuring diverse renewable energy sources. Onshore wind and floating solar power have been successfully delivered, and offshore wind procurement contracts have been signed, ensuring stable and low-carbon energy supply that lays a strong foundation for long-term sustainability goals.

Winbond is extending its governance throughout the entire supply chain to build a resilient and sustainable ecosystem. In 2025, Winbond partnered with supply chain stakeholders to complete a “Large Leads Small” decarbonization project, jointly reducing 19,995 tCO_2e of carbon emissions during the project. We also promoted the adoption of the PACT guidelines among outsourced manufacturers for carbon footprint information exchange, advancing carbon data transparency and collaboration—making low-carbon transformation not only an internal responsibility but a shared commitment across the entire industry chain. As a result of these efforts, Winbond was selected as a “Low-Carbon Achievement Demonstration Enterprise” by the Industrial Development Administration, Ministry of Economic Affairs, and was honored as a “Outstanding Green Procurement / Net zero Green Lifestyle Unit” by both the Kaohsiung City and Taichung City Environmental Protection Bureaus, highlighting Winbond’ s leadership in supply chain governance.

Winbond Group Overview

About the Winbond Group

Winbond Electronics Corporation (“Winbond”) provides global customers with comprehensive niche memory solutions. Its core product portfolio comprises Code Storage Flash Memory, TrustME® Secure Flash, and Customized Memory Solutions (CMS).

Nuvoton Technology Corporation (“Nuvoton”), a subsidiary of Winbond, was established following the spin-off of Winbond’s logic IC business. Nuvoton focuses on microcontrollers (MCUs) and logic ICs, strengthening the Group’s overall solution capabilities.

The Winbond Group is committed to advancing green semiconductor technologies and represents a rare global combination of memory and logic businesses. It is the only semiconductor group in Taiwan with integrated capabilities across CMS, Flash, and Logic process development, product design, and marketing. By leveraging cross-product synergies, the Group delivers diversified and integrated solutions, reinforcing the stability and resilience of its operating foundation.

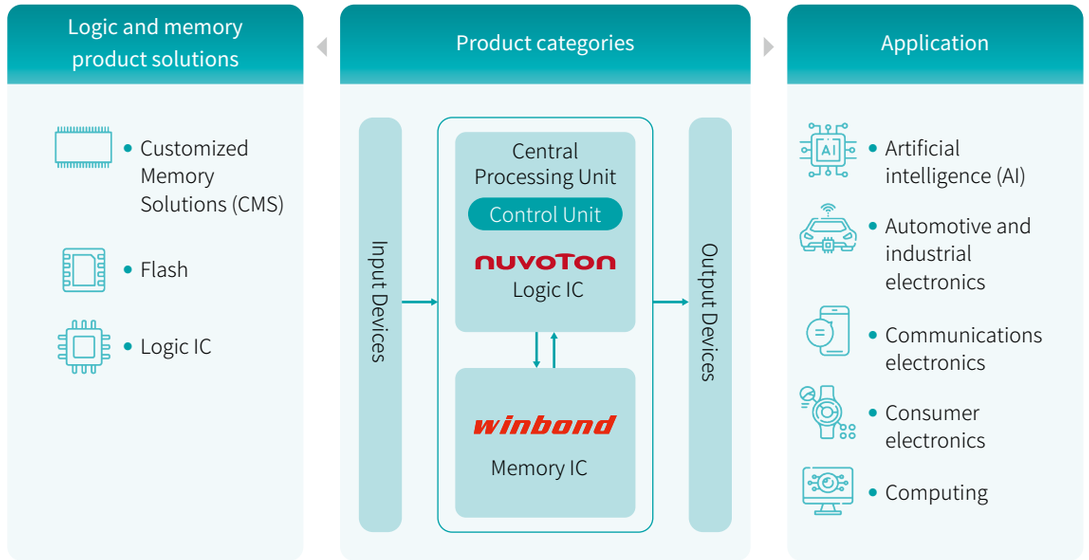
Winbond’s memory business focuses on the design, manufacturing, servicing, and sales of niche memory products, offering customized specifications tailored to diverse customer requirements. The logic business spans a broad range of applications, including microcontroller and voice solutions, cloud security, image sensing, battery monitoring, Internet of Things (IoT) applications, semiconductor components, and wafer foundry services.

Culture: Integrity in operations | accountable teamwork | passionate learning | proactive innovation | sustainable contribution

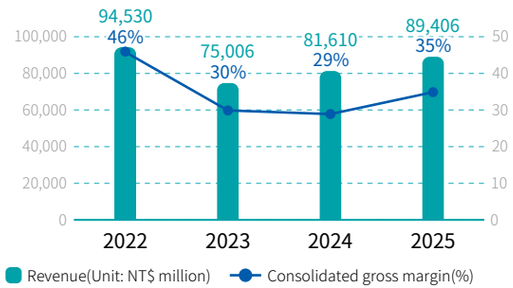
Vision: *Be a hidden champion in providing sustainable semiconductors to enrich human life.*

Industry Position

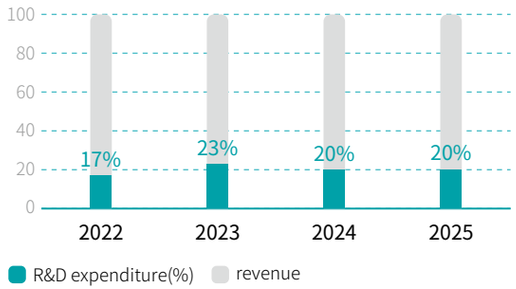
NOR Flash, QSPI NOR Flash, and MOSFET for mobile applications. ★ ranking **No. 1** ★



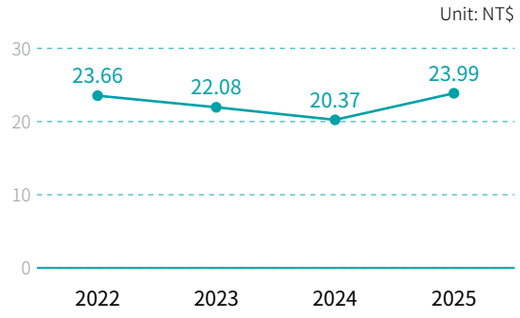
Logic and memory products operating performance



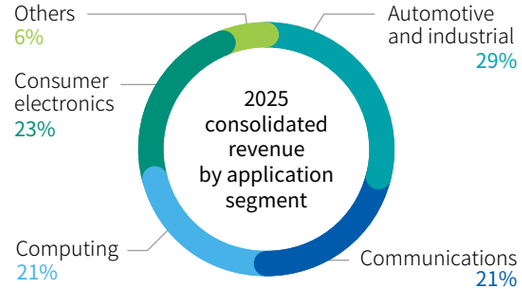
Investment in research and development – R&D expenditure as a percentage of revenue



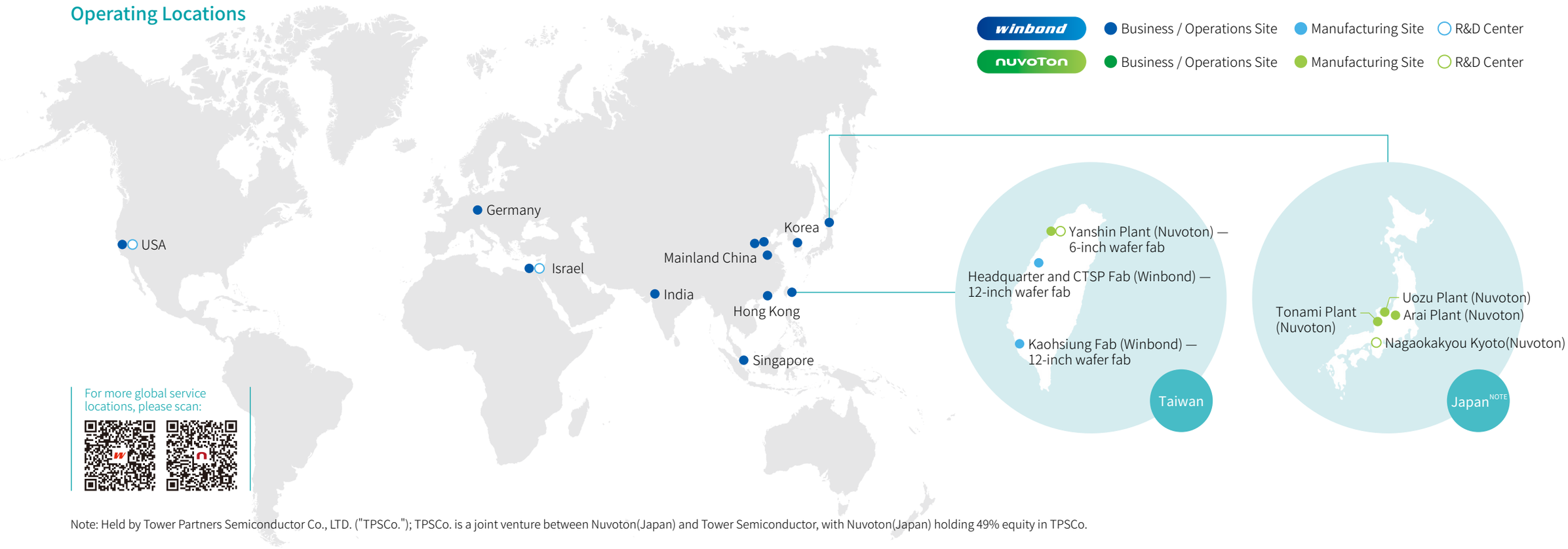
Company value – Net asset value per share



2025 consolidated revenue by application segment



Operating Locations



For more global service locations, please scan:

Note: Held by Tower Partners Semiconductor Co., LTD. ("TPSCo."); TPSCo. is a joint venture between Nuvoton(Japan) and Tower Semiconductor, with Nuvoton(Japan) holding 49% equity in TPSCo.

Global Operating Sites
34

Employees Worldwide
8,131

Manufacturing Sites
6

Manufacturing sites

The Winbond Group operates two 12-inch wafer fabs and one 6-inch wafer fab, complemented by three major manufacturing sites in Japan.

Global operations

Headquartered in Taiwan, the Group maintains operational presence across Taiwan, Mainland China/Hong Kong, Japan, Singapore, South Korea, India, the United States, Germany, and Israel.

Milestones

1987
Founded in Hsinchu Science Park

1995
Listed on the Taiwan Stock Exchange (stock code: 2344)

2006
Launched Multi I/O SpiFlash (Dual in 2006; Quad in 2007), achieving industry-leading performance

2008
Logic IC business spun off to establish Nuvoton Technology

2009
Mass production of the industry's first 16Mb QSPI Flash using 90 nm process technology

2010
Introduced wafer-level chip scale packaging (WLCSP) for serial NOR Flash

2013
Launched QSPI NAND with continuous read embedded ECC and bad block management

2014
Became the world's leading serial NOR Flash supplier and introduced SpiStack products

2017
Launched the first ultra-low-voltage 1.2V 8Mb QSPI NOR Flash

2018
Became the world's No. 1 NOR Flash supplier and introduced high-performance QSPI NAND for automotive applications

2020
Nuvoton acquired Panasonic Semiconductor Business in Japan and renamed it Nuvoton Technology Corporation Japan

2024
- Commercialized the first products manufactured with renewable energy
- Winbond (Taiwan) and Nuvoton (Taiwan) achieved RBA VAP Platinum certification
- Received multiple national sustainability awards

2025
- Selected for the S&P Global Sustainability Yearbook
- Achieved CDP A List ratings for Climate Change and Water Security, with Supplier Engagement Assessment Leadership
- Named among Clarivate Top 100 Global Innovators

⌘ Unless otherwise specified, the scope of disclosure refers to Winbond.

Winbond Group Value

Looking Ahead: Realizing the Long-Term Value of Semiconductors

Facing the global waves of digitalization, low-carbon transformation, and intelligent technologies, the Winbond Group continues to identify the key trends shaping next-generation semiconductor products. The Group sustains its investment in semiconductor design, process technology, and product innovation, striving to achieve the optimal balance among performance, energy efficiency, and sustainability.

Design and R&D Priorities

- Reducing the generation and emission of hazardous substances during manufacturing
- Shortening manufacturing cycle times
- Lowering production costs

Product Innovation Advantages

- Using low-carbon raw materials
- Enhancing product performance
- Improving energy efficiency in product use
- Reducing energy consumption in production
- Enabling smaller form factors

Driving R&D and Process Innovation to Build Efficient and Sustainable Semiconductor Products

Winbond Group's product development focuses on the following key directions:

Enhancing Product Performance	Manufacturing IC products with higher computational efficiency and enhanced performance.	1
Improving Quality	Continuously improving product quality through three major aspects: quality control, reliability assurance, and failure analysis.	2
Controlling Pollution	Reducing the use of consumables during the manufacturing process to lower carbon emissions. Establishing a hazardous substance management system for products, reducing or eliminating harmful substances contained in products through a "process-oriented" approach.	3
Layout of Patents and Intellectual Property Protection	Adopting international standards at the internal proposal stage of patent applications to enhance patent quality and application success rates. Strengthening the protection of intellectual property rights through internal education and training, signing of confidentiality agreements, and other measures.	4
Ensuring Information Security and Confidentiality	Strengthening information security technologies and continuously providing advanced product security function designs.	5
Achieving Smaller Size	Continuously developing process technologies to reduce wafer chip size compared to the previous generation of products.	6
Reducing Production Energy Consumption	Continuously scaling down processes to increase the number of dies produced per wafer, thereby reducing production emissions per die.	7

Technology-Driven Innovation for Everyday Life

Automotive Electronics

From vehicle body and power systems to infotainment systems, intelligent driving, and advanced safety systems, these technologies are applied in emerging electric vehicles to enable a safer, smarter, and more environmentally friendly transportation ecosystem.

Applications

- Vehicle-to-Everything (V2X)
- Advanced Driver-Assistance Systems (ADAS)
- Vehicle Instrument Clusters
- In-Vehicle Infotainment (IVI)
- Telematics
- Automotive Sensing Components
- Automotive Gateways
- Smart Vehicles / Electric Vehicles
- Obstacle Detection
- Human Behavior Recognition

Industrial Electronics

Enhances industrial systems with higher performance, information security, and advanced safety through intelligent connectivity, remote monitoring, human–machine interaction, and on-site machine learning capabilities.

Applications

- Real-Time Sales Information Devices
- Smart Factories
- Smart Meters
- Programmable Logic Controllers (PLC)
- Graphical Human–Machine Interfaces (HMI)
- Industrial Gateways
- Industrial Machine Vision
- Industrial Computers
- Unmanned Aerial Vehicles (UAV)
- Surveillance Cameras
- Medical Endoscopes
- Fan Motors
- Computer Hardware Monitoring

5G Communications

Provides higher data transmission speeds, forming a foundational platform for the Internet of Things and enabling seamless communication across locations to enhance work efficiency, entertainment, and learning experiences.

Applications

- Network Digital Video Converters
- High-Speed Ethernet Switches
- Wireless Terminal Access Devices and Customer Premises Equipment (CPE)
- Long-Term Evolution (LTE)
- LTE/5G Base Stations
- Optical Fiber Communications

Smart IoT

In an interconnected world, accelerates digital transformation while ensuring information security and functional safety, enabling greater energy efficiency, convenience, and enhanced levels of safety protection in daily life.

Applications

- Smart Cities
- Smart Transportation Systems
- Autonomous Vehicles
- Smart Factories
- Telemedicine
- Smart Homes
- Smart Meters
- Smart IoT
- Servers
- Edge Computing
- Conference Systems

Consumer Electronics

Delivers more powerful, energy-efficient, and feature-rich consumer products, enhancing overall user experience.

Applications

- Smartphones
- Smartwatches
- AR Smart Glasses
- Tablet Computers
- Smart TVs
- Smart Homes
- Satellite Navigation Systems
- Digital Cameras
- True Wireless Earbuds
- Set-Top Boxes
- Autonomous Service Robots (Obstacle Detection)
- Intelligent Interactive Toys (Human Behavior Recognition)

Awards and Recognition

⌘ Scope of coverage: Unless otherwise specified, the scope refers to Winbond. Items marked with * apply to the Winbond Group.

永續肯定

S&P Global Sustainability Yearbook

- Selected for the S&P Global Sustainability Yearbook for two consecutive years

FTSE4Good (Financial Times Stock Exchange Sustainability Index)

- Selected as a constituent of the FTSE4Good Emerging Index and the FTSE4Good TIP Taiwan ESG Index

CDP (Carbon Disclosure Project)

- Achieved A List ratings for Climate Change and Water Security, and received Supplier Engagement Assessment – Leadership level

EcoVadis

- Awarded Silver Medal by the global supply chain sustainability assessment platform

RBA (Responsible Business Alliance)

- Winbond (Taiwan) achieved – Platinum level, the highest certification

Ministry of Environment (Taiwan)

- Kaohsiung Fab received the 7th National Enterprise Environmental Protection Award – Silver Award; Central Taiwan Fab and Kaohsiung Fab recognized as Outstanding Green Procurement Units

Business Weekly

- Nuvoton (Taiwan) selected as one of Top 100 Carbon Competitive Enterprises
- Nuvoton (Taiwan) achieved Gold level

Southern Taiwan Science Park Administration, National Science and Technology Council

- Awarded Sustainable Management Award; Kaohsiung Fab awarded Outstanding Occupational Safety and Health Unit; Kaohsiung Fab awarded Outstanding Energy Conservation Unit

Ministry of Economic Affairs (Taiwan)

- Kaohsiung Fab awarded the Energy Conservation Benchmark Award – Gold Award

CommonWealth Sustainability – Carbon Reduction Thermometer

- Ranked No. 1 in Taiwan’ s semiconductor industry

Taiwan Institute for Sustainable Energy (TAISE)

- Winbond awarded TCSA Taiwan Corporate Sustainability Award – Sustainability Report Platinum Award; Nuvoton (Taiwan) awarded TCSA Taiwan Corporate Sustainability Award – Comprehensive Sustainability Performance Award, Taiwan Top 100 Sustainable Enterprises, and Sustainability Report Gold Award

Corporate Governance and Index Recognition

12th Corporate Governance Evaluation

- Ranked within the top 6%–20% among listed companies

Taiwan Index Company*

- Selected as a constituent of the Taiwan High Salary 100 Index, Corporate Governance 100 Index, and Taiwan Employment 99 Index

Innovation, Intellectual Property, and Excellence Awards

Clarivate*

- Selected for the Clarivate Top 100 Global Innovators for three consecutive years

International Convention on Quality Control Circles (ICQCC)

- Awarded the Highest Honor – Gold Award

Industrial Development Administration, Ministry of Economic Affairs*

- Passed TIPS A-Level Certification

EE Awards Asia

- Awarded EE Awards Asia 2025 – Technology Excellence Award and Technology Platform Award (Best Security Platform of the Year); Nuvoton (Taiwan): NuMicro® M2354 Chip-Level Physical Security MCU awarded EE Awards Taiwan – Best MCU of the Year

Taiwan Intellectual Property Office

- Ranked 18th in domestic corporate invention patent applications and 11th in domestic corporate invention patent grants in 2025

Taiwan Continuous Improvement Activity (TCIA)

- Awarded 1 Gold Tower Award, 3 Silver Tower Awards, and 1 Bronze Tower Award

International Standards and Certifications

Certification Item	Winbond CTSP	Winbond Kaohsiung Fab	Yanshin Plant	Nuvoton Japan
ISO 9001 Quality Management System	✓	✓	✓	✓
QC 080000 Hazardous Substance Process Management	✓	✓	✓	–
IATF 16949 Automotive Quality Management System	✓	✓	✓	–
ISO 26262 Road Vehicle Functional Safety	✓	✓	–	–
ISO 21434 Road Vehicle Cybersecurity	✓	✓	–	✓
ISO/IEC 27001 Information Security Management System	✓	✓	✓	✓
ISO 14001 Environmental Management System	✓	✓	✓	✓
ISO 50001 Energy Management System	✓	✓	✓	✓
ISO 46001 Water Efficiency Management System	✓	✓	–	–
ISO 14064-1 Greenhouse Gas Inventory	✓	✓	✓	✓
ISO 14067 Product Carbon Footprint	✓	✓	✓	✓
ISO 14046 Product Water Footprint	✓	✓	–	–
ISO 45001 Occupational Health and Safety Management System	✓	✓	✓	✓
TOSHMS Taiwan Occupational Safety and Health Management System	✓	✓	✓	–

For full certificates and verification statements, please refer to the ESG website download section.

Sustainability Highlights

- **SBTi** has validated Winbond Group's science-based emissions reduction targets.
- **63.14 Million** kWh total renewable energy consumption, representing a **43%** year-on-year increase.
- **100%** of Winbond's manufacturing sites are certified to the UL 2799 Platinum Zero Waste to Landfill standard.
- **PFAS-Free** product portfolio launched, delivering cumulative carbon reduction benefits of approximately **35,044 tCO_2e** through green power manufacturing.
- **Product Carbon Footprint Information** is available to customers through Winbond's corporate website, enhancing convenience and transparency.
- **38 species**：Established Taiwan's largest living Camellia germplasm conservation bank.
- **CDP A List** recognition for Climate Change and Water Security, plus an A (Leadership) rating in Supplier Engagement Assessment (SEA) within Winbond.

- **100%** completion rate of global human rights due diligence, with full employee training coverage.
- **Top 20%** average non-manager employee salary ranking among listed semiconductor peers.
- **NT$29.02 Million** total investment in social contribution programs.
- **3,197** volunteer service participations recorded.
- **3,691** hours of volunteer leave granted to employees.
- **1,002+ kg** of waste removed through **cumulative**

- **NT$1.2 Billion** Board-approved renewable energy investment plan to support long-term transition.
- **11,200+** cumulative approved patents, underscoring long-term technology leadership.
- **3 Years Selected consecutively as a Clarivate Top 100 Global Innovator**
- **240%** overachievement in "Large Leads Small" low carbon and smart transformation project, delivering **19,995 tCO_2e** emissions reduction.
- **100%** supplier sustainability due diligence completion rate.
- **100%** on-site audits and improvement guidance completed for Tier-1 critical suppliers, including third-party verification.
- **57** group-wide digital and AI training sessions to strengthen workforce digital capabilities.
- **NT$4.28 Million** annual interest expense savings achieved through sustainability-linked loans (SLL).